

Product Summary

$V_{(BR)DSS}$	$R_{DS(ON)}$ max	I_D max $T_A = +25^\circ\text{C}$
60V	1.8Ω @ $V_{GS} = 5V$	470mA
	2.4Ω @ $V_{GS} = 3V$	

Description and Applications

DMN61D8LVT provides a single component solution for switching inductive loads such as relays, solenoids, and small DC motors in automotive applications, without the need of a freewheeling diode. DMN61D8LVT accepts logic level inputs, thus allowing it to be driven by logic gates, inverters and microcontrollers. It is ideally suited for door, window and antenna relay coils.



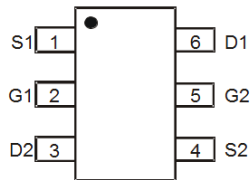
ESD protected up to 2kV

ESD Protected

TSOT26



Top View



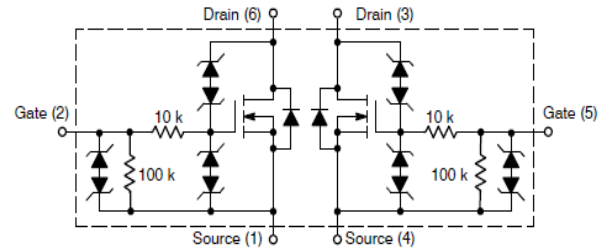
Top View
Internal Schematic

Features and Benefits

- Provides a reliable and robust interface between sensitive logic and DC relay coils
- Replaces 3 to 4 discrete components enabling PCB footprint to be reduced
- Internal active clamp removes the need for external zener diode
- **Totally Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 standards for High Reliability**
- **PPAP Capable (Note 4)**

Mechanical Data

- Case: TSOT26
- Case Material: Molded Plastic, "Green" Molding Compound; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals Connections: See Diagram
- Terminals: Finish – Matte Tin Annealed over Copper Leadframe; Solderable per MIL-STD-202, Method 208③
- Weight: 0.013 grams (Approximate)



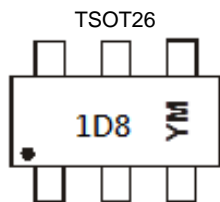
Equivalent Circuit

Ordering Information (Note 5)

Part Number	Case	Packaging
DMN61D8LVTQ-7	TSOT26	3,000/Tape & Reel
DMN61D8LVTQ-13	TSOT26	10,000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to http://www.diodes.com/quality/product_grade_definitions/.
 5. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



1D8 = Product Type Marking Code
 YM = Date Code Marking
 Y or \bar{Y} = Year (ex: B = 2014)
 M = Month (ex: 9 = September)

Date Code Key

Year	2014	2015	2016	2017	2018	2019	2020
Code	B	C	D	E	F	G	H

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Units
Drain-Source Voltage			V _{DSS}	60	V
Gate-Source Voltage			V _{GSS}	±12	V
Continuous Drain Current (Note 7)	Steady State	T _A = +25°C	I _D	630	mA
		T _A = +70°C		500	
Maximum Continuous Body Diode Forward Current (Note 7)			I _S	0.5	A
Single Pulse Drain-to-Source Avalanche Energy (For Relay's Coils/Inductive Loads of 80Ω or Higher) (T _J Initial = +85°C)			EZ	200	mJ
Peak Power Dissipation, Drain-to-Source (Non repetitive current square pulse 1.0 ms duration) (T _J Initial = +85°C)			PPK	20	W
Load Dump Pulse, Drain-to-Source, R _{SOURCE} = 0.5Ω, T = 300 ms (For Relay's Coils/Inductive Loads of 80Ω or Higher) (T _J Initial = +85°C)			ELD1	60	V
Inductive Switching Transient 1, Drain-to-Source (Waveform: R _{SOURCE} = 10Ω, T = 2.0 ms) (For Relay's Coils/Inductive Loads of 80Ω or Higher) (T _J Initial = +85°C)			ELD2	100	V
Inductive Switching Transient 2, Drain-to-Source (Waveform: R _{SOURCE} = 4.0Ω, T = 50 μs) (For Relay's Coils/Inductive Loads of 80Ω or Higher) (T _J Initial = +85°C)			ELD3	300	V
Reverse Battery, 10 Minutes (Drain-to-Source) (For Relay's Coils/Inductive Loads of 80Ω or more)			Rev-Bat	-14	V
Dual Voltage Jump Start, 10 Minutes (Drain-to-Source)			Dual-Volt	28	V
ESD Human Body Model (HBM)			ESD	4,000	V

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

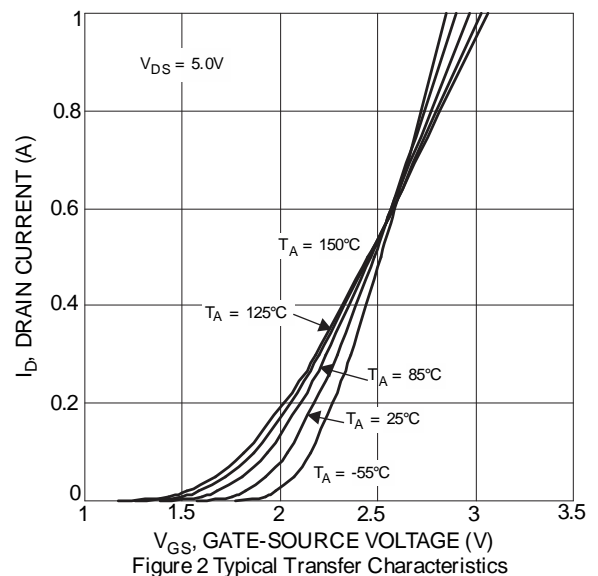
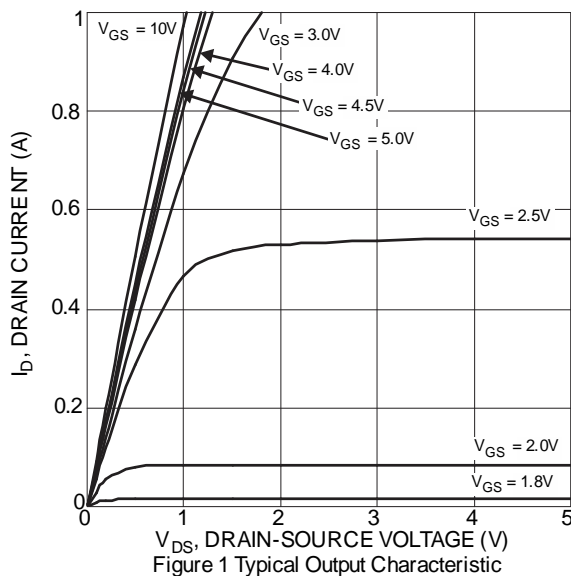
Characteristic			Symbol	Value	Units
Total Power Dissipation (Note 6)			P _D	820	mW
Thermal Resistance, Junction to Ambient (Note 6)	Steady State		R _{θJA}	154	°C/W
Total Power Dissipation (Note 7)			P _D	1,090	mW
Thermal Resistance, Junction to Ambient (Note 7)	Steady State		R _{θJA}	116	°C/W
Operating and Storage Temperature Range			T _J , T _{STG}	-55 to +150	°C

Notes: 6. Device mounted on FR-4 PCB, with minimum recommended pad layout.
7. Device mounted on 1" x 1" FR-4 PCB with high coverage 2oz. copper, single sided.

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)						
Drain-Source Breakdown Voltage	BV _{DSS}	60	—	—	V	V _{GS} = 0V, I _D = 10mA
Zero Gate Voltage Drain Current	I _{DSS}	—	—	50 0.5	μA	V _{DS} = 60V, V _{GS} = 0V V _{DS} = 12V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	±90 ±60	μA	V _{GS} = ±5V, V _{DS} = 0V V _{GS} = ±3V, V _{DS} = 0V
ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	V _{GS(th)}	1.3	—	2.0	V	V _{DS} = V _{GS} , I _D = 1mA
Static Drain-Source On-Resistance	R _{DS(ON)}	—	1.1	1.8	Ω	V _{GS} = 5V, I _D = 0.15A
			1.4	2.4		V _{GS} = 3V, I _D = 0.15A
Forward Transfer Admittance	Y _{fs}	80	—	—	ms	V _{DS} = 12V, I _D = 0.15A
Diode Forward Voltage	V _{SD}	—	—	1.2	V	V _{GS} = 0V, I _S = 0.15A
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	C _{iss}	—	12.9	—	pF	V _{DS} = 12V, V _{GS} = 0V f = 1.0MHz
Output Capacitance	C _{oss}	—	17	—	pF	
Reverse Transfer Capacitance	C _{rss}	—	0.84	—	pF	V _{GS} = 5V, V _{DS} = 12V, I _D = 150mA
Total Gate Charge	Q _g	—	0.74	—	nC	
Gate-Source Charge	Q _{gs}	—	0.19	—	nC	V _{DD} = 12V, V _{GS} = 5V.
Gate-Drain Charge	Q _{gd}	—	0.16	—	nC	
Turn-On Delay Time	t _{D(on)}	—	131	—	ns	
Turn-On Rise Time	t _r	—	301	—	ns	
Turn-Off Delay Time	t _{D(off)}	—	582	—	ns	
Turn-Off Fall Time	t _f	—	440	—	ns	

Notes: 8. Short duration pulse test used to minimize self-heating effect.
9. Guaranteed by design. Not subject to product testing



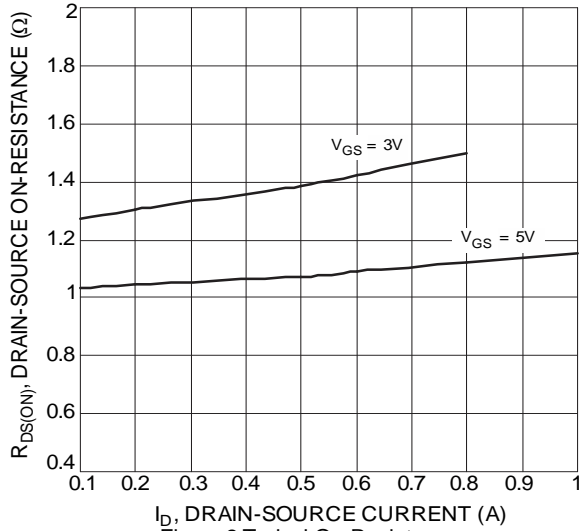


Figure 3 Typical On-Resistance vs. Drain Current and Gate Voltage

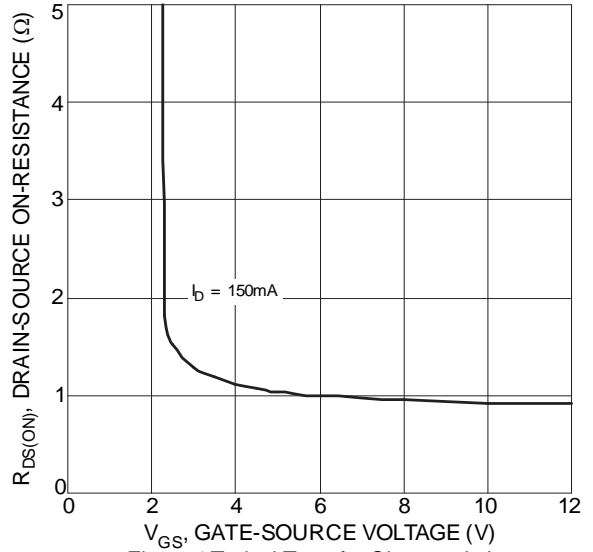


Figure 4 Typical Transfer Characteristic

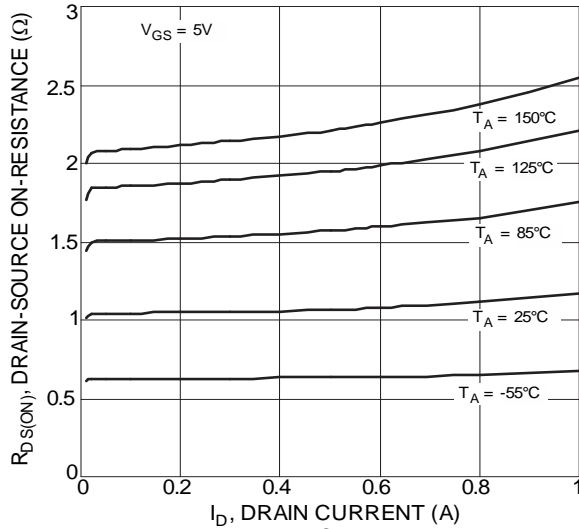


Figure 5 Typical On-Resistance vs. Drain Current and Temperature

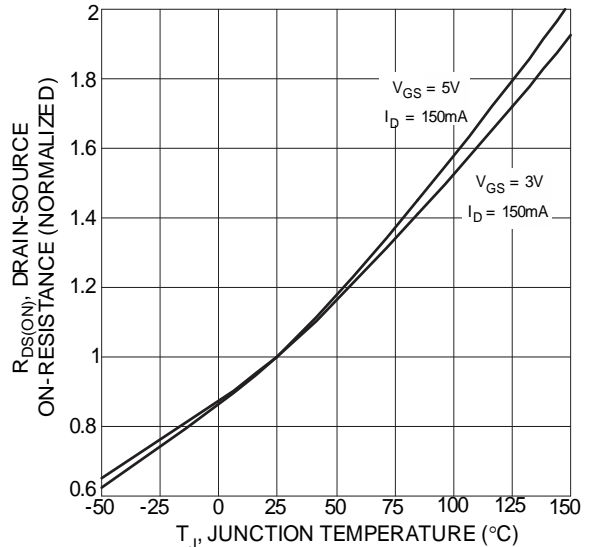


Figure 6 On-Resistance Variation with Temperature

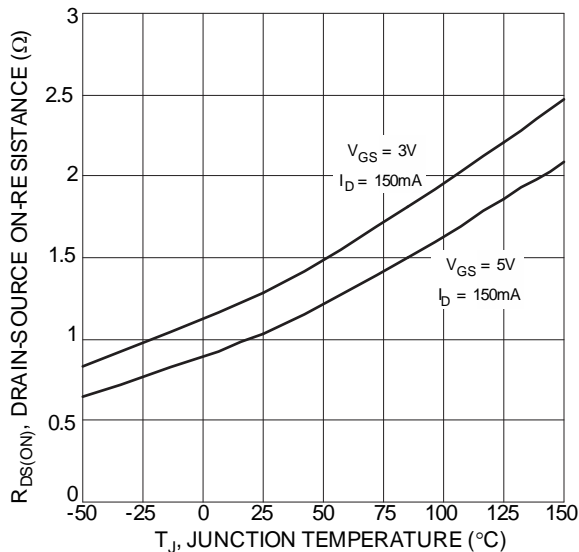


Figure 7 On-Resistance Variation with Temperature

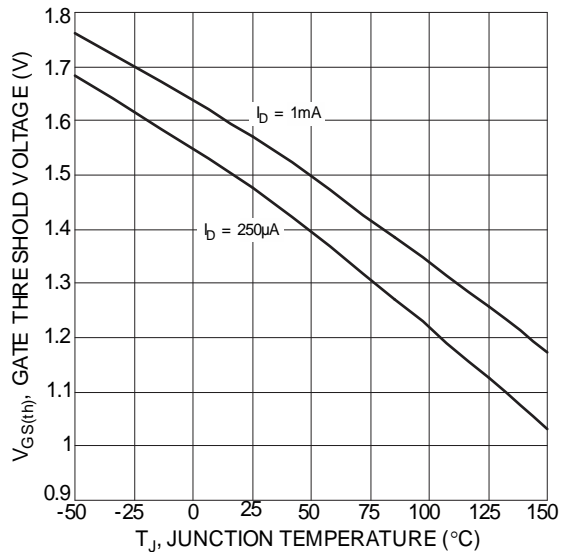


Figure 8 Gate Threshold Variation vs. Ambient Temperature

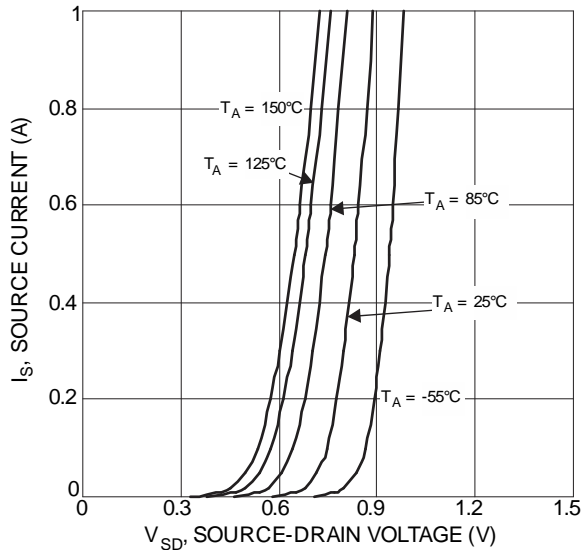


Figure 9 Diode Forward Voltage vs. Current

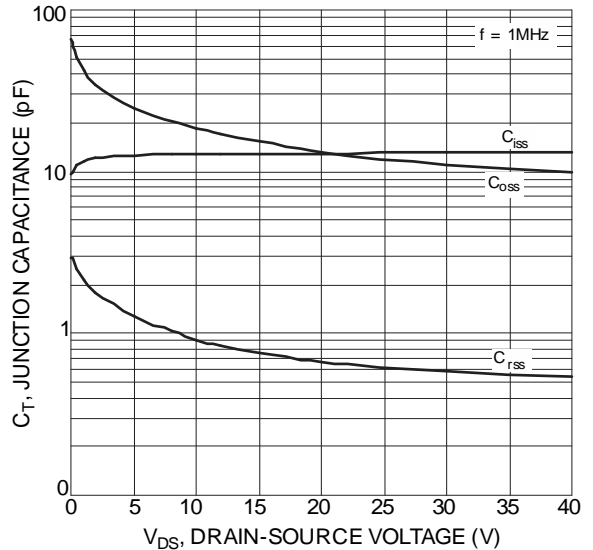


Figure 10 Typical Junction Capacitance

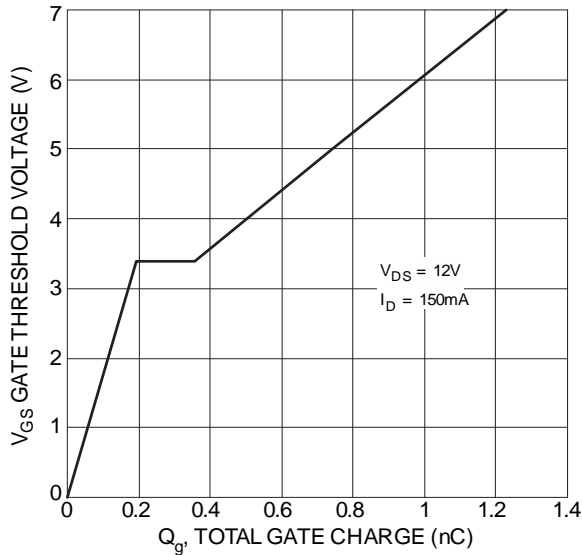


Figure 11 Gate Charge

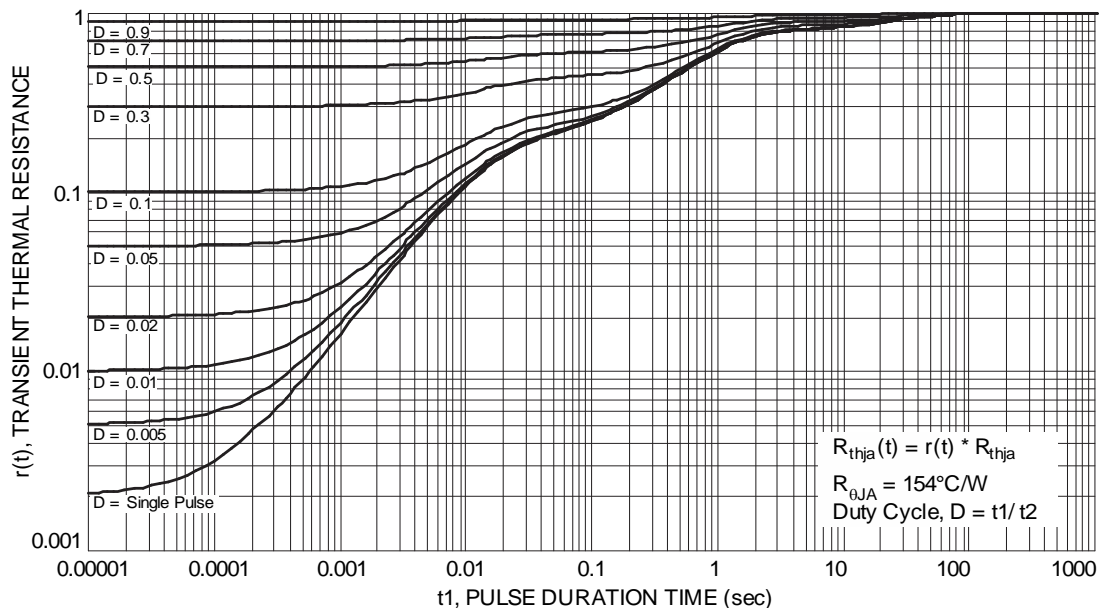


Figure 12 Transient Thermal Resistance

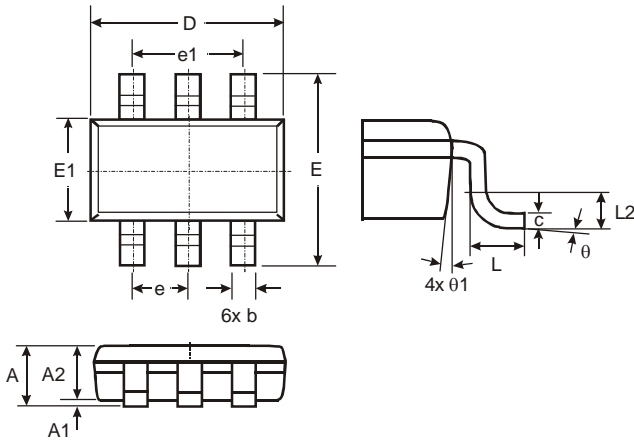
$$R_{thja}(t) = r(t) * R_{thja}$$

$$R_{0JA} = 154^{\circ}\text{C/W}$$

$$\text{Duty Cycle, } D = t1/t2$$

Package Outline Dimensions

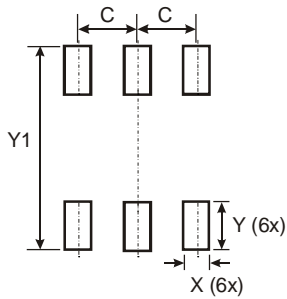
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



TSOT26			
Dim	Min	Max	Typ
A	-	1.00	-
A1	0.01	0.10	-
A2	0.84	0.90	-
D	-	-	2.90
E	-	-	2.80
E1	-	-	1.60
b	0.30	0.45	-
c	0.12	0.20	-
e	-	-	0.95
e1	-	-	1.90
L	0.30	0.50	
L2	-	-	0.25
θ	0°	8°	4°
θ1	4°	12°	-
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	0.950
X	0.700
Y	1.000
Y1	3.199

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